IN THE CLAIMS:

Claims 2 and 4 through 12 were previously withdrawn from consideration and are cancelled herein. Claims 1 and 3 have been amended herein. All of the pending claims are presented below. Please enter these claims as amended.

1. (Currently amended) An electronic device assembly for a substrate having circuits thereon comprising:

an integrated circuit semiconductor die having at least one bond pad thereon for attachment in one of a conventional die attach to lead frame connect process and a LOC connect process;

a conductive plastic lead frame having a plurality of lead fingers, ~~said~~ the conductive plastic lead frame including a plastic lead frame structure having a conductive polymeric material located on at least a portion of ~~said~~ the plurality of lead fingers and formed by one of compression molding and injection molding, a portion of each of the plurality of lead fingers formed for contacting a circuit of ~~said~~ the circuits of ~~said~~ the substrate;

an adhesive attaching a portion of ~~said~~ the integrated circuit semiconductor die to a portion of ~~said~~ the conductive plastic lead frame;

at least one connector connecting ~~said~~ the at least one bond pad of ~~said~~ the integrated circuit semiconductor die to at least one lead finger of ~~said~~ the plurality of lead fingers of ~~said~~ the conductive plastic lead frame; and

encapsulating material for encapsulating at least a portion of ~~said~~ the integrated circuit semiconductor die and for encapsulating at least a portion of the at least one lead finger of ~~said~~ the conductive plastic lead frame.

2. (Currently cancelled)

3. (Currently amended) An electronic device assembly for a substrate having a plurality of circuits thereon comprising:

an integrated circuit semiconductor die having at least one bond pad thereon for attachment in one of a conventional die attach to lead frame connect process and a LOC connect process;

a conductive plastic lead frame having a plurality of lead fingers, ~~said~~ the conductive plastic lead frame including a plastic lead frame structure having a conductive polymeric material located on at least a portion of ~~said~~ the plurality of lead fingers, a portion of each of the plurality of lead fingers formed for contacting a circuit of ~~said~~ the circuits of ~~said~~ the substrate;

an adhesive for attaching a portion of ~~said~~ the integrated circuit semiconductor die to a portion of ~~said~~ the conductive plastic lead frame;

at least one connector connecting ~~said~~ the at least one bond pad of ~~said~~ the integrated circuit semiconductor die to at least one lead finger of ~~said~~ the conductive plastic lead frame; and

encapsulating material for encapsulating at least a portion of ~~said~~ the integrated circuit semiconductor die and for encapsulating at least a portion of ~~said~~ the at least one lead finger of ~~said~~ the conductive plastic lead frame.

4.-12. (Currently cancelled)